

Wafer level Packaging - Global Market Outlook (2017-2026)

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Abstracts

According to Statistics MRC, the global Wafer level Packaging Equipment market is estimated at \$3.12 billion in 2017 and is projected to reach \$15.21 billion by 2026, at a CAGR of 19.2%. The increasing demand for high-speed and compact size of electronic products has expanded the need for wafer-level packaging market. In addition, Internet of Things (IoT) has been gaining popularity and is considered as the third wave of technology. The rising popularity of IoT and portable electronics market is expected to foster the high growth of the wafer-level packaging industry. Moreover, WLP's technological superiority over traditional packaging techniques and the impending need of circuit miniaturization in microelectronic devices acts as drivers of the market growth. However, encapsulation being a challenge for fan-out wafer-level packaging and high initial investment functions is key constraints to the market.

Packaging industry has made strides in terms of design incorporating functionality into the mix. Packaging has encompassed almost all the industries in the world and they have individually experienced a shift in their packaging designs. Innovations in packaging have become key to keeping up with the changing needs of the consumers as well as the manufacturers. One of the most interesting industries to incorporate packaging innovation into their operations is the semiconductor and technology industry. Wafer-level packaging (WLP) is used for interconnecting electronic components, such as capacitors, transistors, resistors, and others onto a single chip to make an integrated circuit, while utilizing deposited solder bumps onto the chip pads.

Based on End User, the electronics segment held steady growth during the forecast period. Imminent need of size reduction in electronics devices, requirement of higher data transmission speed, and improvement in efficiency collectively fuel the replacement of conventional packaging with WLP in electronics industry. By geography,

Asia Pacific held the largest market and will continue to show due to the rising disposable incomes in the market. This is accredited to the presence of various manufacturing facilities, high consumption, and production of electronic products where WLP is steadily replacing wire bond and ongoing R&D. The growing adoption of smartphones in India will permit the market to experience a tumultuous rise in demand. The production of wafer level packaging will be focused more in the APAC region.

Some of the key players in Wafer Level packaging equipment market are Jiangsu Changjiang Electronics Technology Co. Ltd, Siliconware Precision Industries, Infineon Technologies AG, Deca Technologies, KLA-Tencor Corration, Nanium SA, and China Wafer Level CSP Co. Ltd, STATS ChipPAC Ltd, Marvell Technology Group Ltd, Amkor Technology Inc, Qualcomm Inc, Fujitsu Ltd, Toshiba Corp, Tokyo Electron Ltd and Applied Materials, Inc.

Integration Types Covered:

Fan-in Wafer Level Chip Scale Package

Fan-in wafer level packaging

Fan-out wafer level packaging

Flip chip

Packaging Technology Covered:

Wafer Level Chip Scale Package (WLCSP)

Nano WLP

3D TSV WLP

5D TSV WLP

Other Packaging Technologies

Bumping Technologies Covered:

Solder bumping

Gold bumping

Copper Bumping

Other Bumping Technologies

End Users Covered:

Mobile & Wireless communications

IT & Telecommunication

Electronics

Automotive

Industrial

Healthcare

Aerospace & Defense

Other End Users

Regions Covered:

North America

US

Canada

Mexico

Europe

Germany

UK

Italy

France

Spain

Rest of Europe

Asia Pacific

Japan

China

India

Australia

New Zealand

South Korea

Rest of Asia Pacific

South America

Argentina

Brazil

Chile

Rest of South America

Middle East & Africa

Saudi Arabia

UAE

Qatar

South Africa

Rest of Middle East & Africa

What our report offers:

Market share assessments for the regional and country level segments

Market share analysis of the top industry players

Strategic recommendations for the new entrants

Market forecasts for a minimum of 9 years of all the mentioned segments, sub segments and the regional markets

Market Trends (Drivers, Constraints, Opportunities, Threats, Challenges, Investment Opportunities, and recommendations)

Strategic recommendations in key business segments based on the market estimations

Competitive landscaping mapping the key common trends

Company profiling with detailed strategies, financials, and recent developments

Supply chain trends mapping the latest technological advancements

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